

# HSP

Recommended P.C.B Layout(Top Side)  
(PCB BOARD TOLERANCE±0.05)

**NOTES:**

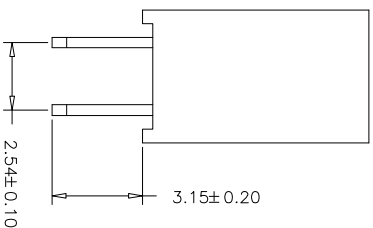
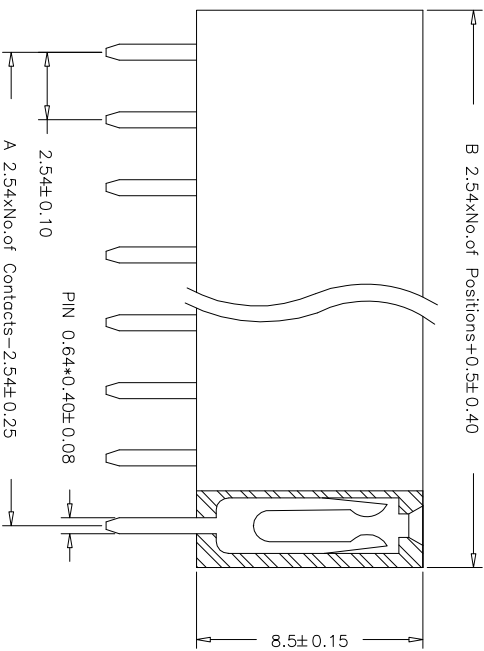
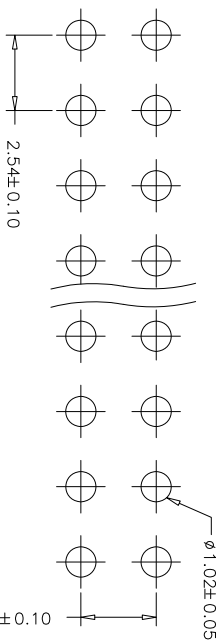
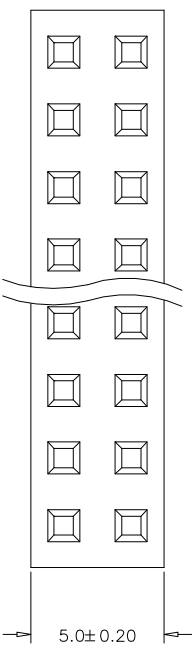
Current Rating: 3.0AMP  
 Contact Resistance: 20mΩ max  
 Withstand Voltage: 500V AC/DC  
 Insulation Resistance: 1000MΩ min  
 Operation Temperature: -40°C to +105°C

Contact Material: JIS C2680-H  
 Contact plating: Au or Sn Over Ni  
 Insulator Material: PBT or PA6T+30%GF(UL94V-0)

## Ordering Information

BT2185 2 XX X A 1 A03

2=Dual Row No.of Pins  
 04-80 Contact Plating Insulation & Packing Contact Shape  
 U=Gold Flash A: PBT + Tray I=Straight  
 X=10u"Gold B: PBT + Tube  
 W=15u"Gold J: PA6T + Tube  
 Y=20u"Gold I: PA6T + Tray  
 Z=30u"Gold  
 F=Gold Flash/Tin  
 A=10u"Gold/Tin  
 J=15u"Gold/Tin  
 K=30u"Gold/Tin  
 S=Tin Plated  
 N=Nickel Plated



Pin No	DIMENSIONS	
	A	B
2*2	2.54	5.58
2*3	5.08	8.12
2*4	7.62	10.66
2*5	10.16	13.20
2*6	12.7	15.74
2*7	15.24	18.28
2*8	17.78	20.82
2*39	96.52	99.56
2*40	99.06	102.1

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION		DRAW	Fany'ijun	09/01/18	SCALE		SHEET	PART NO.	TITLE:
					XX	±0.45				UNIT	mm			
A0	09/01/18	NEW			X XX	±0.30	DESIGN				A4	1/1	BT2185XXXXA1A03	FH254 Dual Row 180H=8.50 Dip=3.15
					X XXX	±0.20	CHECK							
					Angle	± 3'	APPROVE							
					DIM	TOL								



BMA TECHNOLOGIES LTD